

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	911	(216/52).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/21 16:11
S2	61593	(quartz or silica) and etch\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 16:37
S3	2206	(quartz or silica) and etch\$3	JPO	OR	OFF	2005/03/16 13:34
S4	2746	((quartz or silica) and etch\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:06
S5	9852	((quartz or silica or glass) and etch\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 14:48
S6	14120	((quartz or silica or glass) and (etch\$3 or polish\$3 or blast\$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:09
S7	2	("20040238487").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:07
S8	17906	((quartz or silica or glass) and (etch\$3 or plasma or polish\$3 or blast\$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:58
S9	222	(216/80).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:11
S10	880	(216/99).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:11

S11	1138	(216/79).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:11
S12	1	(ultrasonic and assisted and etch). ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:23
S13	7	(quartz or silica or SiO2 or "SiO.sub. 2" or (silicon adj dioxide)) and etch\$3 and ultrasonic\$4 and acid	JPO	OR	OFF	2005/03/16 13:36
S14	5097	(quartz or silica or SiO2 or "SiO.sub. 2" or (silicon adj dioxide)) and etch\$3 and ultrasonic\$4 and acid	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 14:54
S15	1158	(quartz or silica or SiO2 or "SiO.sub. 2" or (silicon adj dioxide)) and etch\$3 and ultrasonic\$4 and acid and roughness	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:36
S16	43	((quartz or silica or SiO2 or "SiO. sub.2" or (silicon adj dioxide)) and etch\$3 and acid and roughness). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:38
S17	3	((quartz or silica or SiO2 or "SiO. sub.2" or (silicon adj dioxide)) and etch\$3 and acid and ultrasonic\$4 and roughness).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:37
S18	739	(438/691).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:49
S19	517	(438/690).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:49
S20	394	(438/704).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:49

S21	932	(438/723).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:49
S22	95	(438/746).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:50
S23	563	(438/756).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:50
S24	16	((quartz or silica or glass) and hydrofluoric and nitric and roughness).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/16 13:59
S27	3	"10059744"	JPO; DERWENT	OR	OFF	2005/03/20 14:23
S30	2	"11106225"	JPO; DERWENT	OR	OFF	2005/03/20 14:24
S31	1	1998-212629.NRAN.	DERWENT	OR	OFF	2005/03/20 14:24
S32	1	1999-307962.NRAN.	DERWENT	OR	OFF	2005/03/20 14:27
S33	31	((quartz or silica or glass) and etch\$3 and grit).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 14:50
S34	31	((quartz or silica or glass) and etch\$3 and (grit or grit-blast\$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 14:48
S35	64	((quartz or silica or glass) and (etch\$3 or acid) and grit).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/30 13:52
S36	7	((quartz or silica or glass) and (etch\$3 or acid) and grit)	JPO	OR	OFF	2005/03/20 15:02
S37	236	(quartz or silica or SiO2 or "SiO.sub. 2" or (silicon adj dioxide)) and etch\$3 and ultrasonic\$4 and acid and grit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 14:54

S38	1	(quartz or silica or SiO2 or "SiO.sub.2" or (silicon adj dioxide)) and (etch\$3 and ultrasonic\$4 and acid and grit).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 14:54
S39	100	(quartz or silica or SiO2 or "SiO.sub.2" or (silicon adj dioxide)) and (etch\$3 and ultrasonic\$4 and acid). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 14:55
S40	30	((quartz or silica or SiO2 or "SiO.sub.2" or (silicon adj dioxide)) and etch\$3 and ultrasonic\$4 and acid). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 14:55
S41	31369	(quartz or silica or glass) and (etch\$3 or acid or roughness)	JPO	OR	OFF	2005/03/20 15:02
S42	7	(quartz or silica or glass) and (etch\$3 or acid or roughness) and grit	JPO	OR	OFF	2005/03/20 15:02
S43	169	(quartz or silica or glass) and (etch\$3 or acid or roughness) and reactor	JPO	OR	OFF	2005/03/20 15:03
S44	205	(quartz or silica or glass) and (etch\$3 or acid or roughness) and ultrasonic	JPO	OR	OFF	2005/03/20 15:04
S45	17	(quartz or silica or glass) and roughness and ultrasonic	JPO	OR	OFF	2005/03/20 15:05
S46	190	(quartz or silica or glass) and (acid or etch\$3) and ultrasonic	JPO	OR	OFF	2005/03/20 15:05
S47	7	(quartz or silica or glass) and (acid or etch\$3) and ultrasonic and rough\$4	JPO	OR	OFF	2005/03/20 15:06
S48	1986	(quartz or silica) and etch\$3 and acid and blast\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 16:43
S49	3	(quartz or silica) and etch\$3 and acid and blast\$3	JPO	OR	OFF	2005/03/20 17:07
S50	61	(quartz or silica) same etch\$3 same acid same blast\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 17:29
S51	1	2004-769023.NRAN.	DERWENT	OR	OFF	2005/03/20 16:53
S52	2	"11106225"	JPO; DERWENT	OR	OFF	2005/03/20 17:45

S53	3	"10059744"	JPO; DERWENT	OR	OFF	2005/03/20 17:48
S54	2	"200189198"	JPO; DERWENT	OR	OFF	2005/03/20 17:53
S55	3	"2001292251"	JPO; DERWENT	OR	OFF	2005/03/20 17:55
S56	2	"2001332462"	JPO; DERWENT	OR	OFF	2005/03/20 17:57
S57	2	(surface and textured and quartz). ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/21 16:14
S58	62	(surface and treatment and quartz). ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/21 16:18
S59	138	(quartz or silica) with (etch\$3 or acid) with ultrasonic\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/25 13:58
S60	31	(etch\$3 adj rate) with ultrasonic\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/21 16:40
S61	2	"2001332462"	JPO; DERWENT	OR	OFF	2005/03/21 16:43
S62	3	"2001292251"	JPO; DERWENT	OR	OFF	2005/03/21 16:44
S63	2	"2003174017"	JPO; DERWENT	OR	OFF	2005/03/21 16:45
S64	1	2003-354682.NRAN.	DERWENT	OR	OFF	2005/03/21 16:45
S65	1	1977-13387Y.NRAN.	DERWENT	OR	OFF	2005/03/25 12:20
S72	386	(quartz or silica or glass) with (etch\$3 or acid) with ultrasonic\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/25 14:37
S74	21	(grit with (mesh adj size)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/25 14:39

S76	434	((quartz or glass or silica) and (roughness with Ra)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/25 14:43
S77	245	((quartz or silica) with (roughness with Ra))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/25 14:45
S78	19	(quartz or silica) with (roughness with Ra) with (etch\$3 or acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/25 14:45
S79	138	(quartz or silica) with (etch\$3 or acid) with ultrasonic\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/25 15:10
S80	138	(quartz or silica) with (etch\$3 or acid) with ultrasonic\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/26 14:34
S81	19	(quartz or silica) with (roughness with Ra) with (etch\$3 or acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/26 15:12
S82	386	(quartz or silica or glass) with (etch\$3 or acid) with ultrasonic\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/26 14:05
S83	20	S82 and (roughness with Ra)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/26 14:06
S84	106	((quartz or silica) and (etch\$3 or acid) and ultrasonic\$4).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/26 14:35
S85	97	(quartz or (silica adj glass)) same ((etch\$3 or acid) with ultrasonic\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/26 14:36

S86	3132	(quartz or silica) with ((grit or grain) adj size)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/26 15:13
S87	205	(quartz or silica) with ((grit or grain) adj size) with (etch\$3 or acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/26 15:13
S88	241	(quartz or silica) with ((grit or grain or mesh) adj size) with (etch\$3 or acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/26 15:14
S89	30	quartz with ((grit or grain or mesh) adj size) with (etch\$3 or acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/26 15:14
S90	758	quartz with ((grit or grain or mesh) adj size)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/26 15:15
S91	1	(quartz with (grit adj blast\$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/26 15:15
S92	2768	((quartz or silica) and etch\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 11:56
S93	33	((quartz or silica) and etch\$3 and dry\$3 and nitrogen).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 11:56
S94	138	(quartz or silica) with (etch\$3 or acid) with ultrasonic\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 13:29
S95	66	(quartz or silica) and (etch\$3 or acid) and ultrasonic\$4	JPO	OR	OFF	2005/03/28 12:36
S96	6	(agitat\$3 or stir\$4) with ultrasonic\$4 with etch\$3	JPO	OR	OFF	2005/03/28 12:37
S97	9	((agitat\$3 or stir\$4) with ultrasonic\$4) same etch\$3	JPO	OR	OFF	2005/03/28 12:37

S98	420	((agitat\$3 or stir\$4) with ultrasonic\$4) same etch\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 12:38
S99	166	((agitat\$3 or stir\$4) with ultrasonic\$4) with etch\$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/03/28 12:52
S10 0	74	S98 and quartz	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/03/28 12:41
S10 1	9194	ultrasonic\$4.ti.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/03/28 12:53
S10 2	422	ultrasonic\$4.ti. and etch\$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/03/28 12:53
S10 3	65	ultrasonic\$4.ti. and etch\$3.clm.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/03/28 12:53
S10 4	515	(quartz or silica) same (etch\$3 or acid) same blast\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 13:30
S10 5	145	((quartz or silica) and (etch\$3 or acid) and blast\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 13:30
S10 6	19	(quartz or silica) with (roughness with Ra) with (etch\$3 or acid)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 17:18
S10 7	386	(quartz or silica or glass) with (etch\$3 or acid) with ultrasonic\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 17:18
S10 8	20	S107 and (roughness with Ra)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 17:18
S10 9	267	((quartz or silica or glass) and (etch\$3 or acid) and blast\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/30 13:53



S11 0	1494	((quartz or silica or glass) same (etch\$3 or acid) same blast\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/30 13:53
S11 1	638	((quartz or silica or glass) with (etch\$3 or acid) with blast\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/30 13:53